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Mullis LDocket No.: M4065.0127/P127-A  
(PATENT)

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Kie Y. Ahn, et al

Application No.: 09/660,324

Group Art Unit: 2581

Filed: September 12, 2000

Examiner: F. Toledo

For: SILICON MULTI-CHIP MODULE  
PACKAGING WITH INTEGRATED  
PASSIVE COMPONENTS AND METHOD  
OF MAKING**REQUEST FOR ACKNOWLEDGEMENT OF FORM PTO-1449**Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In reviewing the above-captioned application file, Applicant has noted that Applicant's Form PTO-1449, which accompanied an Information Disclosure Statement filed on September 12, 2000, has not yet been initialed by the Examiner. The Examiner is therefore requested to kindly return the initialed forms to the undersigned as soon as possible.

Dated: March 25, 2003

Respectfully submitted,

By \_\_\_\_\_  
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